

Coded Note Number: **Y1660**

Revision: **C001**

Date: **September 25, 2017**

Title: **ELECTRONIC EQUIPMENT MANUFACTURING CONTROL (EEMC)  
PROGRAM**

**This revision history is provided for convenience and does not alleviate the supplier's responsibility with understanding and complying with the full coded note.**

**Change from Revision A – Editorial change to reformat to current standard.**

**Bolded font indicates changed/added content.**

**[Text deleted] inserted in the document indicates the removal of content.**

- 1) The vendor is required to implement and maintain an Electronic Equipment Manufacturing Control (EEMC) program in accordance with the following specifications (as applicable):

|                 |  |
|-----------------|--|
| MIL-STD-454H    | Standard General Requirement for Electronic Equipment (Less Reqmts)                                      |
| MIL-STD-275D    | Print Wiring for Electronic Equipment  |
| MIL-P-55110C    | Print Wire Boards  |
| WS-6536D        | Process Specification Procedures and Requirements for Preparation and Soldering of Electrical Connection |
| NAVMAT P-4855.1 | Navy Power Supply Reliability  |
| DOD STD-1686    | Electro Static Discharge Control   |

The vendor is required to provide to the shipbuilder a list identifying which of the specifications here in pertain to the subject P.O. for example, NAVMAT P-4855.1 is only applicable to P.O.'s that include a power supply.

- 2) An Environmental Stress Screening for Electronic Hardware (esseh) program is to be implemented by the vendor in accordance with NAVSEA Note 3900.
- 3) ESSEH is to be tailored for specific equipment design criteria and operating conditions using NAVMAT P-9492 for guidance.
- 4) ESSEH programs are to be established only for equipment/components containing solid state devices. Where a solid state module is part of a major assembly, only the solid state module will be subject to ESSEH.
- 5) ESSEH is to be accomplished at the part level and the component level as part of the manufacturing process.

- 6) ESSEH screening at the subassembly level is acceptable in lieu of the part level in cases where it can be shown to be more cost effective to screen at the subassembly level.
- 7) The ESSEH program must be dynamic in nature and structured so that maximum screening effectiveness is obtained. The manufacturing process (including process control procedures and in-process tests and inspections) shall be adjusted to minimize recurrence of defects found during stress screening. Cost models, yield and rework data, and failure data shall be maintained to demonstrate cost effectiveness of the program.
- 8) The vendor is required to provide an ESSEH procedure to the shipbuilder for approval prior to implementation.
- 9) The specifications referenced herein have precedence over all similar documents otherwise referenced throughout the P.O. and on individual equipment drawings. However, where the drawings or specification specify a limit, tolerance or dimension, the existing requirements shall prevail.